CLAIMS

1. A continuous process for the partial demetallization of a first multilayer substrate, comprising at least one metallic layer (21), characterised in that a designed lacquer comprising at least one metal dissolving etchant (25), locally reacts with said metallic layer (21) and that the dissolved metal remains within said multilayer structure and that the dissolution of the metal allows the creation of a window in said metallic layer without the necessity of a washing step and in that said partial demetallization is suitable to be carried out on standard gravure or flexo printing presses or coating equipment.

2. Process as in claim 1 characterised in that said process further comprises a lamination step of the partly demetallized multilayer support with at least one second substrate.

3. Process as in claim 1 or 2 characterised in that at least one of said substrates are selected from the group consisting of polymeric films, paper, metallic foils and non-woven substrates.

4. Process as in claim 1 or 2 characterised in that at least one of said substrates are treated by at least one coating operation and/or at least one printing operation.

5. Process as in claim 4 characterised in that said coating or printing operation is carried out on a different substrate surface than that where the demetallization is carried out, yet involves a patterned print or coating in register with the demetallized area and/or the other printed designs in or on the multilayer structure.

6. Process as in claim 1, characterised in that the demetallization step achieves a light transmission

of at least 90% within the demetallized area without a washing step.

7. Process as in claim 1, characterised in that the demetallization step to obtain a light transmission of at least 90% is carried out on standard gravure or flexo printing presses or coating equipment without necessitating a specific dedicated equipment for demetallization.

8. Process as in claim 1 characterised in that the etchant concentration in the etchant lacquer (25) substantially corresponds to the stoechiometrical amount of said etchant to dissolve the amount of metal present on the film.

9. Process as in claim 1, characterised in that the etchant concentration in the etchant lacquer (25) corresponds to a slight excess of the stoechiometrical amount of said etchant to dissolve the amount of metal present on the film.

10. Multilayer support obtainable by any of the previous claims comprising windows in continuous and/or discontinuous supported metallic layers characterised in that said windows contain the total quantity of the residues resulting from the demetallization by means of an etching product.